

IN THE CLAIMS:

Cancel claims 3, 8, 9, 10, 22, 26, 27, and 28.

Claims 1, 5, 17, 19, 23, and 25 have been amended herein. All of the pending claims 1, 2, 4 through 7, 11 through 21, 23 through 25, and 29 through 36 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Currently Amended) A multi-chip module system comprising:
a substrate having at least a first position having, in turn, a predetermined configuration for locating a first semiconductor device thereat and having at least one other vacant position having, in turn, a predetermined configuration for locating a second semiconductor device thereat on the multi-chip module system, the at least one other vacant position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position; and
a first semiconductor device located in the at least first position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; said first semiconductor device has been burned in at said at least first position on said substrate.
2. (Previously Presented) The multi-chip module system of claim 1, further comprising:
the at least one other vacant position having the predetermined configuration for locating the second semiconductor device thereat which is substantially the same as the predetermined configuration of the first position.
3. (Canceled)

4. (Previously Presented) The multi-chip module system of claim 1, further comprising:
the at least one other vacant position having the predetermined configuration for locating the second semiconductor device thereat; and
the second semiconductor device having a second predetermined performance characteristic of at least substantially twice that of the first predetermined performance characteristic of the first semiconductor device.

5 (Currently Amended) A multi-chip module system comprising:
a substrate having a first position having, in turn, a predetermined configuration for locating a first semiconductor device thereat, having a second position having, in turn, a predetermined configuration for locating a second semiconductor device thereat, and having at least one other vacant position having, in turn, a predetermined configuration for locating a third semiconductor device thereat on the multi-chip module system, the at least one other vacant position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
the first semiconductor device located in the first position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; and
the second semiconductor device located in the second position of the substrate for use in the multi-chip module system, the second semiconductor device having a second predetermined performance characteristic; said first and second semiconductor devices have been burned in at said first and second positions, respectively, on said substrate.

6. (Previously Presented) The multi-chip module system of claim 5, further comprising:
the at least one other vacant position having a predetermined configuration for locating a third semiconductor device thereat which is substantially the same as the predetermined configuration of the first position.

7. (Previously Presented) The multi-chip module system of claim 5, further comprising:
the at least one other vacant position having a predetermined configuration for locating a third semiconductor device thereat; and
the third semiconductor device having a predetermined performance characteristic substantially similar to that of the first predetermined performance characteristic of the first semiconductor device.

8. (Canceled)

9. (Canceled)

10. (Canceled)

11. (Previously Presented) The multi-chip module system of claim 5, wherein the first semiconductor device comprises a memory device.

12. (Previously Presented) The multi-chip module system of claim 5, wherein the second semiconductor device comprises a memory device.

13. (Previously Presented) The multi-chip module system of claim 5, wherein the first semiconductor device comprises a microprocessor device.

14. (Previously Presented) The multi-chip module system of claim 5, wherein the second semiconductor device comprises a microprocessor device.

15. (Previously Presented) The multi-chip module system of claim 5, wherein the multi-chip module system comprises a single in-line memory module system.

16. (Previously Presented) The multi-chip module system of claim 5, further comprising:
a third semiconductor device; and
an adapter connected to the third semiconductor device, the adapter having a configuration for connecting the adapter to the at least one other vacant position on the substrate to allow connection of the third semiconductor device to the substrate.

17. (Currently Amended) A multi-chip module system comprising:
a substrate having two opposing sides, said substrate having a first position having, in turn, a predetermined configuration for locating a first semiconductor device thereat, having a second position having, in turn, a predetermined configuration for locating a second semiconductor device thereat, having a first vacant position having, in turn, a predetermined configuration for locating a third semiconductor device thereat, the first vacant position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position, and having a second vacant position having, in turn, a predetermined configuration for locating a fourth semiconductor device thereat on the multi-chip module system, the second vacant position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
the first semiconductor device located in the first position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; and
the second semiconductor device located in the second position of the substrate for use in the multi-chip module system, the second semiconductor device having a second predetermined performance characteristic; said first and second semiconductor devices being burned in at said first and second positions, respectively, on said substrate.

18. (Previously Presented) The multi-chip system module of claim 17, wherein:
the first vacant position and the second vacant position are on opposing sides of the substrate.

19. (Currently Amended) A multi-chip module system comprising:
a substrate having at least a first predetermined configuration position for locating a first semiconductor device thereat and having at least one other vacant predetermined configuration position for locating a second semiconductor device thereat on the multi-chip module system, the at least one other vacant position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position; and
the first semiconductor device located in the at least the first predetermined configuration position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; said first semiconductor device being burned in at said first predetermined configuration position on said substrate.

20. (Previously Presented) The multi-chip module system of claim 19, further comprising:
the at least one other vacant predetermined configuration position for locating the second semiconductor device thereat which is substantially the same as the predetermined configuration of the first position.

21. (Previously Presented) The multi-chip module system of claim 19, further comprising:
the at least one other vacant predetermined configuration position having a predetermined configuration for locating the second semiconductor device thereat; and
the second semiconductor device having a predetermined performance characteristic substantially similar to that of the first predetermined performance characteristic of the first semiconductor device.

22. (Canceled)

23. (Currently Amended) A multi-chip module system comprising:
a substrate having a first predetermined configuration position for locating a first semiconductor device thereat, having a second predetermined configuration position for locating a second semiconductor device thereat, and having at least one other vacant predetermined configuration position for locating a third semiconductor device thereat on the multi-chip module system, the at least one other vacant position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
the first semiconductor device located in the first predetermined configuration position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; and
the second semiconductor device located in the second predetermined configuration position of the substrate for use in the multi-chip module system, the second semiconductor device having a second predetermined performance characteristic; wherein said first and second semiconductor devices being burned in at said first and second predetermined configuration positions, respectively, on said substrate.

24. (Previously Presented) The multi-chip module system of claim 23, further comprising:
the at least one other vacant predetermined configuration position for locating the third semiconductor device thereat which is substantially the same as the predetermined configuration of the first position.

25. (Previously Presented) The multi-chip module system of claim 23, further comprising:
the at least one other vacant predetermined configuration position for locating the third semiconductor device thereat; and
the third semiconductor device having a third predetermined performance characteristic substantially similar to that of the first predetermined performance characteristic of the first semiconductor device.

26. (Canceled)
27. (Canceled)
28. (Canceled)
29. (Original) The multi-chip module system of claim 23, wherein the first semiconductor device comprises a memory device.
30. (Original) The multi-chip module system of claim 23, wherein the second semiconductor device comprises a memory device.
31. (Original) The multi-chip module system of claim 23, wherein the first semiconductor device comprises a microprocessor device.
32. (Original) The multi-chip module system of claim 23, wherein the second semiconductor device comprises a microprocessor device.
33. (Original) The multi-chip module system of claim 23, wherein the multi-chip module system comprises a single in-line memory module system.
34. (Previously Presented) The multi-chip module system of claim 23, further comprising:
an adapter connected to the third semiconductor device, the adapter having a configuration for connecting the adapter to the at least one other vacant predetermined configuration position on the substrate to allow connection of the third semiconductor device to the substrate.

35. (Currently Amended) A multi-chip module system comprising:
a substrate having two opposing sides, said substrate having a first predetermined configuration position for locating a first semiconductor device thereat, having a second predetermined configuration position for locating a second semiconductor device thereat, having a first vacant predetermined configuration position for locating a third semiconductor device thereat, the first vacant predetermined configuration position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position, and having a second vacant predetermined configuration position for locating a fourth semiconductor device thereat on the multi-chip module system, the second vacant predetermined configuration position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
the first semiconductor device located in the first predetermined configuration position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; and
the second semiconductor device located in the second predetermined configuration position of the substrate for use in the multi-chip module system, the second semiconductor device having a second predetermined performance characteristic; said first and second semiconductor devices have been burned in at said first and second predetermined configuration positions, respectively, on said substrate.

36. (Previously Presented) The multi-chip system module of claim 35, wherein:
the first vacant predetermined configuration position and the second vacant predetermined configuration position are located on opposing sides of the substrate.